



Product Change Notification: MFOL-15XOSS098

Date:

12-Sep-2025

Product Category:

Platform Root Of Trust Controllers

Notification Subject:

CCB 7175 Final Notice: Qualification of ATP7 as an additional assembly site for CEC1734-S0-I/2HW, CEC1734-I/2HW-MD, CEC1734-S0-I/2HW-TFLX-PROTO, CEC1734-S0-I/2HW-TCSM-PROTO, CEC1734-S0-I/2HW-TFLX, CEC1736-S0-I/2HW, CEC1736-S0-I/2HW-PROTO, CEC1736-S0-I/2HW-PROTO2, CEC1736-I/2HW-MD, CEC1736-S0-I/2HW-QU001, CEC1736-S0-I/2HW-TFLX-PROTO, CEC1736-S0-I/2HW-TFLX, CEC1736-S0-I/2HW-TCSM-PROTO, CEC1736-S0-I/2HW-MA000, CEC1734-S0-I/2HW-MA000, CEC1736-I/2HW-MDC, CEC1734-I/2HW-MDC, CEC1736-S0-I/2HW-TCSM and CEC1734-S0-I/2HW-TCSM catalog part numbers (CPN) available in 64L VFBGA (5.5x5.5x0.92mm) package.

Affected CPNs:

[MFOL-15XOSS098_Affected_CPN_09122025.pdf](#)

[MFOL-15XOSS098_Affected_CPN_09122025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for CEC1734-S0-I/2HW, CEC1734-I/2HW-MD, CEC1734-S0-I/2HW-TFLX-PROTO, CEC1734-S0-I/2HW-TCSM-PROTO, CEC1734-S0-I/2HW-TFLX, CEC1736-S0-I/2HW, CEC1736-S0-I/2HW-PROTO, CEC1736-S0-I/2HW-PROTO2, CEC1736-I/2HW-MD, CEC1736-S0-I/2HW-QU001, CEC1736-S0-I/2HW-TFLX-PROTO, CEC1736-S0-I/2HW-TFLX, CEC1736-S0-I/2HW-TCSM-PROTO, CEC1736-S0-I/2HW-MA000, CEC1734-S0-I/2HW-MA000, CEC1736-I/2HW-MDC, CEC1734-I/2HW-MDC, CEC1736-S0-I/2HW-TCSM and CEC1734-S0-I/2HW-TCSM catalog part numbers (CPN) available in 64L VFBGA (5.5x5.5x0.92mm) package.

Pre and Post Summary Changes:

		Pre Change	Post Change	
Assembly Site		Amkor Assembly & Test (Shanghai) Co., LTD/ (ANAC)	Amkor Assembly & Test (Shanghai) Co., LTD/ (ANAC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
Substrate	Core Material	HL832NXA	HL832NXA	HL832NXA
	SM Material	AUS320	AUS320	AUS320
Wire Material		CuPdAu	CuPdAu	CuPdAu
Die Attach Material	Die #1*	EM760L2-P	EM760L2-P	EM760L2-P
	Die #2*	EM760L2-P	EM760L2-P	EM760L2-P
	Die #3**	ATB-F125E	ATB-F125E	ATB-F125E
Mold Compound		G750E	G750E	G770FE
Solder Ball Material		SAC305	SAC305	SAC305

Note*: Die 1 and Die 2 is only applicable to CEC1734-S0-I/2HW, CEC1734-I/2HW-MD, CEC1734-S0-I/2HW-TFLX-PROTO, CEC1734-S0-I/2HW-TCSM-PROTO, CEC1734-S0-I/2HW-MA000, CEC1734-I/2HW-MDC, CEC1734-S0-I/2HW-TCSM and CEC1734-S0-I/2HW-TFLX catalog part numbers using the same die attach material (EM760L2-P).

Note**: Die 1, Die 2, and Die 3 are only applicable to CEC1736-S0-I/2HW, CEC1736-S0-I/2HW-PROTO, CEC1736-S0-I/2HW-PROTO2, CEC1736-I/2HW-MD, CEC1736-S0-I/2HW-QU001, CEC1736-S0-I/2HW-TFLX-PROTO, CEC1736-S0-I/2HW-TFLX, CEC1736-I/2HW-MDC, CEC1736-S0-I/2HW-TCSM, CEC1736-S0-I/2HW-MA000 and CEC1736-S0-I/2HW-TCSM-PROTO catalog part numbers using EM760L2-P and ATB-F125E die attach material.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 17 October 2025 (date code: 2542)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	September 2024					>	September 2025					October 2025			
Work Week	36	37	38	39	40		36	37	38	39	40	41	42	43	44
Initial PCN Issue Date				x											
Qual Report Availability								x							
Final PCN Issue Date								x							
Estimated Implementation Date													x		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: September 25, 2024: Issued initial notification.
 September 12, 2025: Issued final notification. Updated the Notification Subject, Description of Change and affected parts list to add CPNs CEC1736-S0-I/2HW-MA000, CEC1734-S0-I/2HW-MA000, CEC1736-I/2HW-MDC, CEC1734-I/2HW-MDC, CEC1736-S0-I/2HW-TCSM and CEC1734-S0-I/2HW-TCSM. Attached the Qualification Report. Provided estimated first ship date to be on October 17, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-15XOSS098_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.